

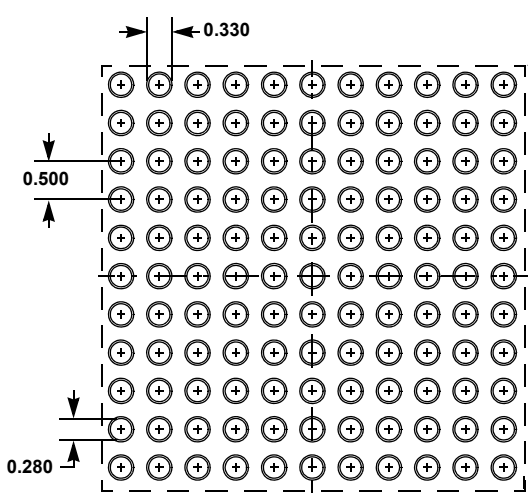
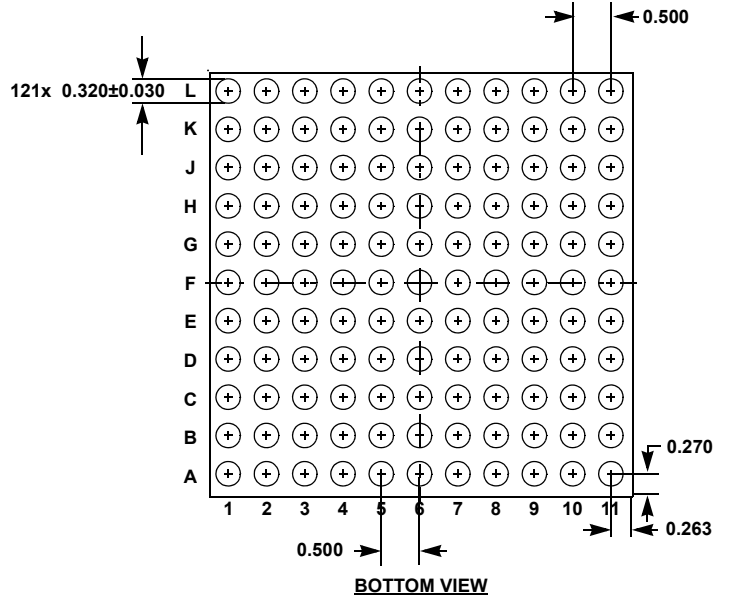
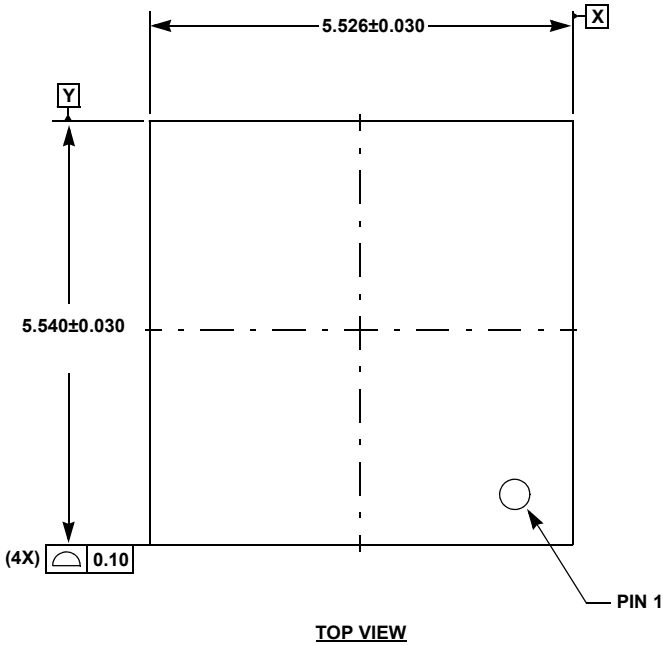
Plastic Packages for Integrated Circuits

Package Outline Drawing

W11x11.121A

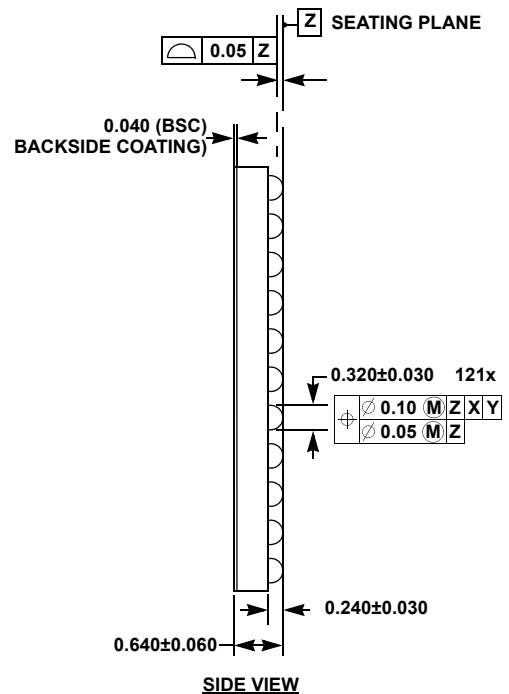
121 BALL WAFER LEVEL CHIP SCALE PACKAGE (WLCSP 0.5mm pitch) (BSC)

Rev 1, 2/14



3 NSMD

TYPICAL RECOMMENDED LAND PATTERN



NOTES:

- All dimensions are in millimeters.
- Dimensions and tolerance per ASMEY 14.5M - 1994 and JESD 95-1, SPP-010.
- 3 NSMD refers to non-solder mask defined pad design per Intersil Techbrief [TB451](#).